

IN THE CLAIMS:

Please amend the claims as shown below. The status of the claims after amendment will be as follows.

Claims 1 - 7 (canceled)

8. (currently amended) A lead-free solder paste comprising a first solder alloy powder of a first solder alloy, a second solder alloy powder of a second solder alloy, and a flux mixed with the first and second solder alloy powders, wherein the first solder alloy and the second solder alloy have a difference of at least 10°C in their main peak temperatures measured by differential thermal analysis, the overall composition after melting of the first and second solder alloy powders is 3 - 4 mass % of Ag, 3 - 10 mass % of In, 0 - 1 mass % of Bi, 0 - 1 mass % of Cu, and a balance of Sn, and the first solder alloy contains 6 - 20 mass % of In.

9. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy is a Sn-Ag-In alloy and the second solder alloy is a Sn-Ag alloy.

10. (previously presented) A solder paste as claimed in claim 9 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 - 20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

11. (previously presented) A solder paste as claimed in claim 8 wherein:

at least one of the first and second solder alloys contains Bi;

the first solder alloy is selected from a Sn-Ag-In alloy and a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag alloy, a Sn-Ag-Bi alloy, a Sn-Ag-Cu alloy, and a Sn-Ag-Bi-Cu alloy.

12. (previously presented) A solder paste as claimed in claim 11 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 - 20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

13. (previously presented) A solder paste as claimed in claim 8 wherein:

the first solder alloy is selected from a Sn-Ag-In alloy and a Sn-Ag-In-Bi alloy; and

the second solder alloy is selected from a Sn-Ag-Cu alloy and a Sn-Ag-Bi-Cu alloy.

14. (previously presented) A solder paste as claimed in claim 13 wherein:

the first solder alloy contains 3 - 4 mass % of Ag and 6 -

20 mass % of In; and

the second solder alloy contains 3 - 4 mass % of Ag.

15. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy has a lower main peak temperature measured by differential thermal analysis than the second solder alloy.

16. (previously presented) A solder paste as claimed in claim 8 wherein the overall composition after melting of the first and second solder alloy powders contains 6 - 10 mass % of In.

17. (previously presented) A solder paste as claimed in claim 8 wherein the difference in the main peak temperatures of the first and second solder alloys is at least 20 °C.

18. (previously presented) A solder paste as claimed in claim 8 wherein the first solder alloy is free of Cu and the second solder alloy contains greater than 0 and at most 1 mass % of Cu.

19. (previously presented) A solder paste as claimed in claim 11 wherein the first solder alloy is a Sn-Ag-In-Bi alloy.

20. (previously presented) A solder paste as claimed in claim 8 wherein the first alloy contains 12 - 20 mass % of In.

21. (previously presented) A solder paste as claimed in claim 8 wherein the second alloy contains greater than 0 and at most 1 mass % of Bi.

22. (previously presented) A solder paste as claimed in claim 8 wherein each of the first and second alloys contains greater than 0 and at most 1 mass % of Bi.

23. (new) A solder paste as claimed in claim 8 wherein:
the first solder alloy contains Sn and 3 - 4 mass % of Ag
and has a lower main peak temperature measured by differential thermal analysis than the second solder alloy, and
the second solder alloy is a In-free alloy containing Sn and
3 - 4 mass % of Ag.